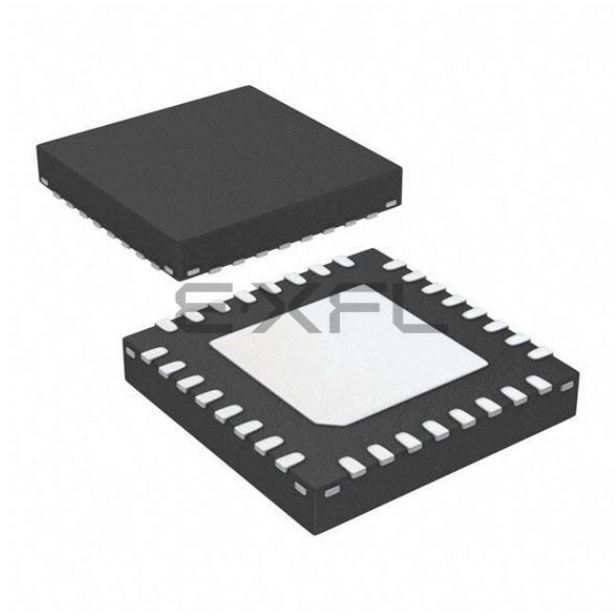

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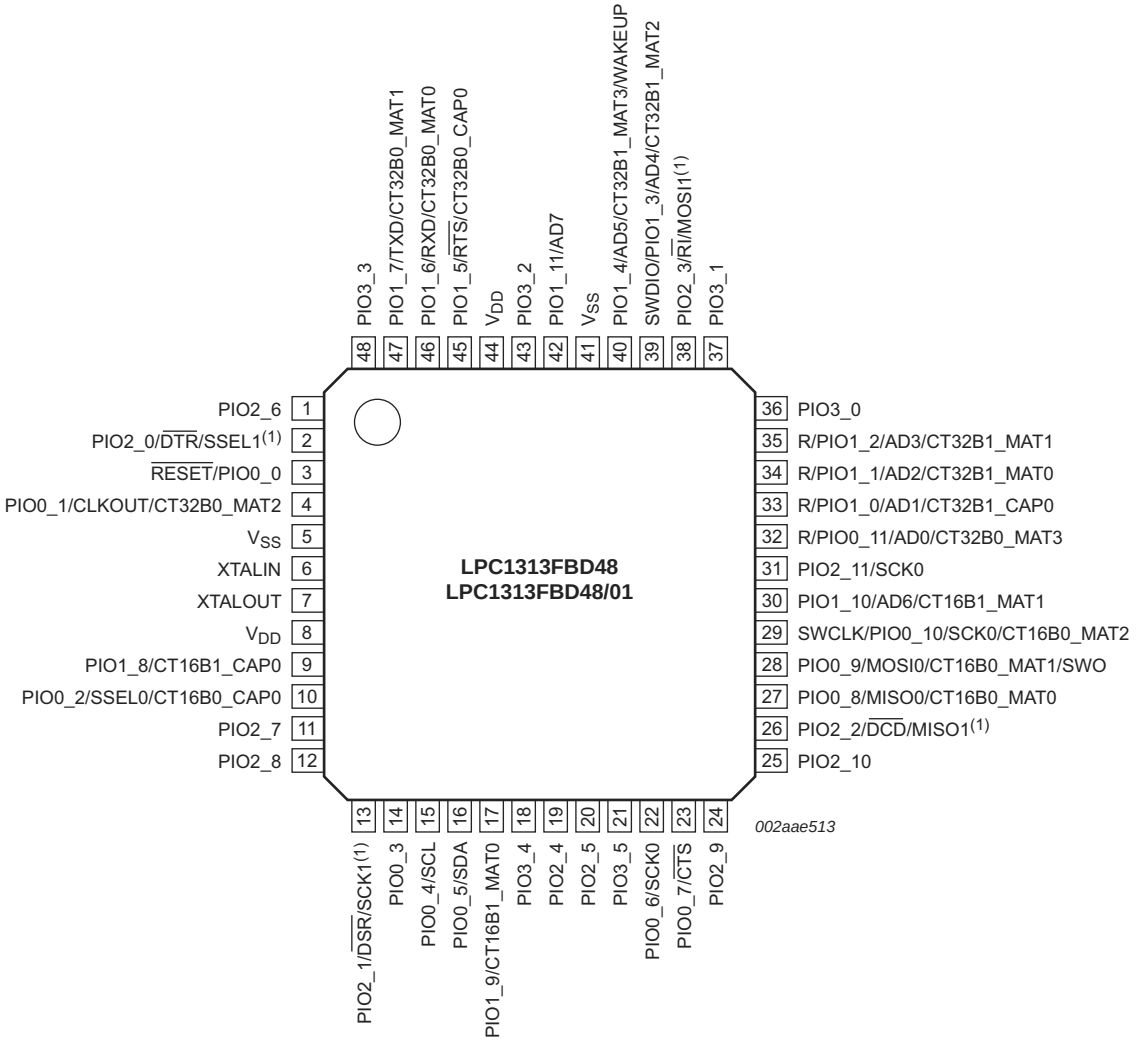
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	72MHz
Connectivity	I²C, Microwire, SPI, SSI, SSP, UART/USART, USB
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	28
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 3.6V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-VQFN Exposed Pad
Supplier Device Package	32-HVQFN (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/lpc1342fhn33-551



(1) SSP1 or UART function on LPC1313FBD48/01 only.

Fig 4. LPC1313 LQFP48 package

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6.2 Pin description

Table 3. LPC1313/42/43 LQFP48 pin description table

Symbol	Pin	Start logic input	Type	Reset state [1]	Description
$\overline{\text{RESET}}$/PIO0_0	3[2]	yes	I	I; PU	**$\overline{\text{RESET}}$ —** External reset input with 20 ns glitch filter. A LOW-going pulse as short as 50 ns on this pin resets the device, causing I/O ports and peripherals to take on their default states, and processor execution to begin at address 0.
			I/O	-	**PIO0_0 —** General purpose digital input/output pin with 10 ns glitch filter.
PIO0_1/CLKOUT/ CT32B0_MAT2/ USB_FTOGGLE	4[3]	yes	I/O	I; PU	**PIO0_1 —** General purpose digital input/output pin. A LOW level on this pin during reset starts the ISP command handler or the USB device enumeration (USB on LPC1342/43 only, see description of PIO0_3).
			O	-	**CLKOUT —** Clockout pin.
			O	-	**CT32B0_MAT2 —** Match output 2 for 32-bit timer 0.
			O	-	**USB_FTOGGLE —** USB 1 ms Start-of-Frame signal (LPC1342/43 only).
PIO0_2/SSEL0/ CT16B0_CAP0	10[3]	yes	I/O	I; PU	**PIO0_2 —** General purpose digital input/output pin.
			I/O	-	**SSEL0 —** Slave select for SSP0.
			I	-	**CT16B0_CAP0 —** Capture input 0 for 16-bit timer 0.
PIO0_3/USB_VBUS	14[3]	yes	I/O	I; PU	**PIO0_3 —** General purpose digital input/output pin. LPC1342/43 only: A LOW level on this pin during reset starts the ISP command handler, a HIGH level starts the USB device enumeration.
			I	-	**USB_VBUS —** Monitors the presence of USB bus power (LPC1342/43 only).
PIO0_4/SCL	15[4]	yes	I/O	I; IA	**PIO0_4 —** General purpose digital input/output pin (open-drain).
			I/O	-	**SCL —** I^2C-bus clock input/output (open-drain). High-current sink only if I^2C Fast-mode Plus is selected in the I/O configuration register.
PIO0_5/SDA	16[4]	yes	I/O	I; IA	**PIO0_5 —** General purpose digital input/output pin (open-drain).
			I/O	-	**SDA —** I^2C-bus data input/output (open-drain). High-current sink only if I^2C Fast-mode Plus is selected in the I/O configuration register.
PIO0_6/ $\overline{\text{USB\_CONNECT}}$/ SCK0	22[3]	yes	I/O	I; PU	**PIO0_6 —** General purpose digital input/output pin.
			O	-	**$\overline{\text{USB\_CONNECT}}$ —** Signal used to switch an external 1.5 kΩ resistor under software control. Used with the SoftConnect USB feature (LPC1342/43 only).
			I/O	-	**SCK0 —** Serial clock for SSP0.
PIO0_7/$\overline{\text{CTS}}$	23[3]	yes	I/O	I; PU	**PIO0_7 —** General purpose digital input/output pin (high-current output driver).
			I	-	**$\overline{\text{CTS}}$ —** Clear To Send input for UART.
PIO0_8/MISO0/ CT16B0_MAT0	27[3]	yes	I/O	I; PU	**PIO0_8 —** General purpose digital input/output pin.
			I/O	-	**MISO0 —** Master In Slave Out for SSP0.
			O	-	**CT16B0_MAT0 —** Match output 0 for 16-bit timer 0.

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Table 3. LPC1313/42/43 LQFP48 pin description table *…continued*

Symbol	Pin	Start logic input	Type	Reset state [1]	Description
PIO0_9/MOSI0/ CT16B0_MAT1/ SWO	28[3]	yes	I/O	I; PU	**PIO0_9 —** General purpose digital input/output pin.
			I/O	-	**MOSI0 —** Master Out Slave In for SSP0.
			O	-	**CT16B0_MAT1 —** Match output 1 for 16-bit timer 0.
			O	-	**SWO —** Serial wire trace output.
SWCLK/PIO0_10/ SCK0/CT16B0_MAT2	29[3]	yes	I	I; PU	**SWCLK —** Serial wire clock.
			I/O	-	**PIO0_10 —** General purpose digital input/output pin.
			I/O	-	**SCK0 —** Serial clock for SSP0.
			O	-	**CT16B0_MAT2 —** Match output 2 for 16-bit timer 0.
R/PIO0_11/ AD0/CT32B0_MAT3	32[5]	yes	-	I; PU	**R —** Reserved. Configure for an alternate function in the IOCONFIG block.
			I/O	-	**PIO0_11 —** General purpose digital input/output pin.
			I	-	**AD0 —** A/D converter, input 0.
			O	-	**CT32B0_MAT3 —** Match output 3 for 32-bit timer 0.
R/PIO1_0/ AD1/CT32B1_CAP0	33[5]	yes	-	I; PU	**R —** Reserved. Configure for an alternate function in the IOCONFIG block.
			I/O	-	**PIO1_0 —** General purpose digital input/output pin.
			I	-	**AD1 —** A/D converter, input 1.
			I	-	**CT32B1_CAP0 —** Capture input 0 for 32-bit timer 1.
R/PIO1_1/ AD2/CT32B1_MAT0	34[5]	yes	-	I; PU	**R —** Reserved. Configure for an alternate function in the IOCONFIG block.
			I/O	-	**PIO1_1 —** General purpose digital input/output pin.
			I	-	**AD2 —** A/D converter, input 2.
			O	-	**CT32B1_MAT0 —** Match output 0 for 32-bit timer 1.
R/PIO1_2/ AD3/CT32B1_MAT1	35[5]	yes	-	I; PU	**R —** Reserved. Configure for an alternate function in the IOCONFIG block.
			I/O	-	**PIO1_2 —** General purpose digital input/output pin.
			I	-	**AD3 —** A/D converter, input 3.
			O	-	**CT32B1_MAT1 —** Match output 1 for 32-bit timer 1.
SWDIO/PIO1_3/ AD4/ CT32B1_MAT2	39[5]	yes	I/O	I; PU	**SWDIO —** Serial wire debug input/output.
			I/O	-	**PIO1_3 —** General purpose digital input/output pin.
			I	-	**AD4 —** A/D converter, input 4.
			O	-	**CT32B1_MAT2 —** Match output 2 for 32-bit timer 1.
PIO1_4/AD5/ CT32B1_MAT3/ WAKEUP	40[5]	yes	I/O	I; PU	**PIO1_4 —** General purpose digital input/output pin.
			I	-	**AD5 —** A/D converter, input 5.
			O	-	**CT32B1_MAT3 —** Match output 3 for 32-bit timer 1.
			I	-	**WAKEUP —** Deep power-down mode wake-up pin with 20 ns glitch filter. This pin must be pulled HIGH externally to enter Deep power-down mode and pulled LOW to exit Deep power-down mode. A LOW-going pulse as short as 50 ns wakes up the part.

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Table 4. LPC1311/13/42/43 HVQFN33 pin description table

Symbol	Pin	Start logic input	Type	Reset state [1]	Description
$\overline{\text{RESET}}$/PIO0_0	2[2]	yes	I	I; PU	**$\overline{\text{RESET}}$ —** External reset input with 20 ns glitch filter. A LOW-going pulse as short as 50 ns on this pin resets the device, causing I/O ports and peripherals to take on their default states, and processor execution to begin at address 0.
			I/O	-	**PIO0_0 —** General purpose digital input/output pin with 10 ns glitch filter.
PIO0_1/CLKOUT/ CT32B0_MAT2/ USB_FTOGGLE	3[3]	yes	I/O	I; PU	**PIO0_1 —** General purpose digital input/output pin. A LOW level on this pin during reset starts the ISP command handler or the USB device enumeration (USB on LPC1342/43 only, see description of PIO0_3).
			O	-	**CLKOUT —** Clock out pin.
			O	-	**CT32B0_MAT2 —** Match output 2 for 32-bit timer 0.
			O	-	**USB_FTOGGLE —** USB 1 ms Start-of-Frame signal (LPC1342/43 only).
PIO0_2/SSEL0/ CT16B0_CAP0	8[3]	yes	I/O	I; PU	**PIO0_2 —** General purpose digital input/output pin.
			I/O	-	**SSEL0 —** Slave select for SSP0.
			I	-	**CT16B0_CAP0 —** Capture input 0 for 16-bit timer 0.
PIO0_3/ USB_VBUS	9[3]	yes	I/O	I; PU	**PIO0_3 —** General purpose digital input/output pin. LPC1342/43 only: A LOW level on this pin during reset starts the ISP command handler, a HIGH level starts the USB device enumeration.
			I	-	**USB_VBUS —** Monitors the presence of USB bus power (LPC1342/43 only).
PIO0_4/SCL	10[4]	yes	I/O	I; IA	**PIO0_4 —** General purpose digital input/output pin (open-drain).
			I/O	-	**SCL —** I^2C-bus clock input/output (open-drain). High-current sink only if I^2C Fast-mode Plus is selected in the I/O configuration register.
PIO0_5/SDA	11[4]	yes	I/O	I; IA	**PIO0_5 —** General purpose digital input/output pin (open-drain).
			I/O	-	**SDA —** I^2C-bus data input/output (open-drain). High-current sink only if I^2C Fast-mode Plus is selected in the I/O configuration register.
PIO0_6/ USB_$\overline{\text{CONNECT}}$/ SCK0	15[3]	yes	I/O	I; PU	**PIO0_6 —** General purpose digital input/output pin.
			O	-	**USB_$\overline{\text{CONNECT}}$ —** Signal used to switch an external 1.5 kΩ resistor under software control. Used with the SoftConnect USB feature (LPC1342/43 only).
			I/O	-	**SCK0 —** Serial clock for SSP0.
PIO0_7/$\overline{\text{CTS}}$	16[3]	yes	I/O	I; PU	**PIO0_7 —** General purpose digital input/output pin (high-current output driver).
			I	-	**$\overline{\text{CTS}}$ —** Clear To Send input for UART.
PIO0_8/MISO0/ CT16B0_MAT0	17[3]	yes	I/O	I; PU	**PIO0_8 —** General purpose digital input/output pin.
			I/O	-	**MISO0 —** Master In Slave Out for SSP0.
			O	-	**CT16B0_MAT0 —** Match output 0 for 16-bit timer 0.
PIO0_9/MOSI0/ CT16B0_MAT1/ SWO	18[3]	yes	I/O	I; PU	**PIO0_9 —** General purpose digital input/output pin.
			I/O	-	**MOSI0 —** Master Out Slave In for SSP0.
			O	-	**CT16B0_MAT1 —** Match output 1 for 16-bit timer 0.
			O	-	**SWO —** Serial wire trace output.

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Table 4. LPC1311/13/42/43 HVQFN33 pin description table *…continued*

Symbol	Pin	Start logic input	Type	Reset state [1]	Description
PIO1_7/TXD/ CT32B0_MAT1	32[3]	yes	I/O	I; PU	**PIO1_7 —** General purpose digital input/output pin.
			O	-	**TXD —** Transmitter output for UART.
			O	-	**CT32B0_MAT1 —** Match output 1 for 32-bit timer 0.
PIO1_8/ CT16B1_CAP0	7[3]	yes	I/O	I; PU	**PIO1_8 —** General purpose digital input/output pin.
			I	-	**CT16B1_CAP0 —** Capture input 0 for 16-bit timer 1.
PIO1_9/ CT16B1_MAT0	12[3]	yes	I/O	I; PU	**PIO1_9 —** General purpose digital input/output pin.
			O	-	**CT16B1_MAT0 —** Match output 0 for 16-bit timer 1.
PIO1_10/AD6/ CT16B1_MAT1	20[5]	yes	I/O	I; PU	**PIO1_10 —** General purpose digital input/output pin.
			I	-	**AD6 —** A/D converter, input 6.
			O	-	**CT16B1_MAT1 —** Match output 1 for 16-bit timer 1.
PIO1_11/AD7	27[5]	yes	I/O	I; PU	**PIO1_11 —** General purpose digital input/output pin.
			I	-	**AD7 —** A/D converter, input 7.
PIO2_0/$\overline{\text{DTR}}$	1[3]	yes	I/O	I; PU	**PIO2_0 —** General purpose digital input/output pin.
			O	-	**$\overline{\text{DTR}}$ —** Data Terminal Ready output for UART.
PIO3_2	28[3]	yes	I/O	I; PU	**PIO3_2 —** General purpose digital input/output pin.
PIO3_4	13[3]	no	I/O	I; PU	**PIO3_4 —** General purpose digital input/output pin (LPC1311/13 only).
PIO3_5	14[3]	no	I/O	I; PU	**PIO3_5 —** General purpose digital input/output pin (LPC1311/13 only).
USB_DM	13[6]	no	I/O	F	**USB_DM —** USB bidirectional D− line (LPC1342/43 only).
USB_DP	14[6]	no	I/O	F	**USB_DP —** USB bidirectional D+ line (LPC1342/43 only).
V_{DD}	6; 29	-	I	-	3.3 V supply voltage to the internal regulator, the external rail, and the ADC. Also used as the ADC reference voltage.
XTALIN	4[7]	-	I	-	Input to the oscillator circuit and internal clock generator circuits. Input voltage must not exceed 1.8 V.
XTALOUT	5[7]	-	O	-	Output from the oscillator amplifier.
V_{SS}	33	-	-	-	Thermal pad. Connect to ground.

[1] Pin state at reset for default function: I = Input; O = Output; PU = internal pull-up enabled (for V_{DD} = 3.3 V, pin is pulled up to 2.6 V for parts LPC1311/13/42/43 and pulled up to 3.3 V for parts LPC1311/01 and LPC1313/01); IA = inactive, no pull-up/down enabled. F = floating; floating pins, if not used, should be tied to ground or power to minimize power consumption.

[2] 5 V tolerant pad. See Figure 37 for pad characteristics. $\overline{\text{RESET}}$ functionality is not available in Deep power-down mode. Use the WAKEUP pin to reset the chip and wake up from Deep power-down mode. An external pull-up resistor is required on this pin for the Deep power-down mode.

[3] 5 V tolerant pad providing digital I/O functions with configurable pull-up/pull-down resistors and configurable hysteresis (see Figure 36).

[4] I^2C-bus pads compliant with the I^2C-bus specification for I^2C standard mode and I^2C Fast-mode Plus.

[5] 5 V tolerant pad providing digital I/O functions with configurable pull-up/pull-down resistors, configurable hysteresis, and analog input. When configured as a ADC input, digital section of the pad is disabled, and the pin is not 5 V tolerant (see Figure 36).

[6] Pad provides USB functions. It is designed in accordance with the USB specification, revision 2.0 (Full-speed and Low-speed mode only). This pad is not 5 V tolerant.

[7] When the system oscillator is not used, connect XTALIN and XTALOUT as follows: XTALIN can be left floating or can be grounded (grounding is preferred to reduce susceptibility to noise). XTALOUT should be left floating.

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7.10 UART

The LPC1311/13/42/43 contains one UART.

Support for RS-485/9-bit mode allows both software address detection and automatic address detection using 9-bit mode.

The UART includes a fractional baud rate generator. Standard baud rates such as 115200 Bd can be achieved with any crystal frequency above 2 MHz.

7.10.1 Features

- Maximum UART data bit rate of 4.5 MBit/s.
- 16-byte receive and transmit FIFOs.
- Register locations conform to 16C550 industry standard.
- Receiver FIFO trigger points at 1 B, 4 B, 8 B, and 14 B.
- Built-in fractional baud rate generator covering wide range of baud rates without a need for external crystals of particular values.
- Fractional divider for baud rate control, auto baud capabilities and FIFO control mechanism that enables software flow control implementation.
- Support for RS-485/9-bit mode.
- Support for modem control.

7.11 SSP serial I/O controller

The LPC1311/13/42/43 contain one SSP controller. An additional SSP controller is available on the LPC1313FBD48/01 package.

The SSP controller is capable of operation on a SSP, 4-wire SSI, or Microwire bus. It can interact with multiple masters and slaves on the bus. Only a single master and a single slave can communicate on the bus during a given data transfer. The SSP supports full duplex transfers, with frames of 4 bits to 16 bits of data flowing from the master to the slave and from the slave to the master. In practice, often only one of these data flows carries meaningful data.

7.11.1 Features

- Maximum SSP speed of 36 Mbit/s (master) or 6 Mbit/s (slave)
- Compatible with Motorola SPI, 4-wire Texas Instruments SSI, and National Semiconductor Microwire buses
- Synchronous serial communication
- Master or slave operation
- 8-frame FIFOs for both transmit and receive
- 4-bit to 16-bit frame

7.12 I^2C-bus serial I/O controller

The LPC1311/13/42/43 contain one I^2C-bus controller.

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7.18.5 Power control

The LPC1311/13/42/43 support a variety of power control features. There are three special modes of processor power reduction: Sleep mode, Deep-sleep mode, and Deep power-down mode. The CPU clock rate may also be controlled as needed by changing clock sources, reconfiguring PLL values, and/or altering the CPU clock divider value. This allows a trade-off of power versus processing speed based on application requirements. In addition, a register is provided for shutting down the clocks to individual on-chip peripherals, allowing fine tuning of power consumption by eliminating all dynamic power use in any peripherals that are not required for the application. Selected peripherals have their own clock divider which provides even better power control.

7.18.5.1 Power profiles (LPC1300L series, LPC1311/01 and LPC1313/01 only)

The power consumption in Active and Sleep modes can be optimized for the application through simple calls to the power profile. The power configuration routine configures the LPC1311/01 and the LPC1313/01 for one of the following power modes:

- Default mode corresponding to power configuration after reset.
- CPU performance mode corresponding to optimized processing capability.
- Efficiency mode corresponding to optimized balance of current consumption and CPU performance.
- Low-current mode corresponding to lowest power consumption.

In addition, the power profile includes routines to select the optimal PLL settings for a given system clock and PLL input clock.

7.18.5.2 Sleep mode

When Sleep mode is entered, the clock to the core is stopped. Resumption from the Sleep mode does not need any special sequence but re-enabling the clock to the ARM core.

In Sleep mode, execution of instructions is suspended until either a reset or interrupt occurs. Peripheral functions continue operation during Sleep mode and may generate interrupts to cause the processor to resume execution. Sleep mode eliminates dynamic power used by the processor itself, memory systems and related controllers, and internal buses.

7.18.5.3 Deep-sleep mode

In Deep-sleep mode, the chip is in Sleep mode, and in addition all analog blocks are shut down. As an exception, the user has the option to keep the watchdog oscillator and the BOD circuit running for self-timed wake-up and BOD protection. Deep-sleep mode allows for additional power savings.

Up to 40 pins total can serve as external wake-up pins to the start logic to wake up the chip from Deep-sleep mode (see Section 7.19.1).

Unless the watchdog oscillator is selected to run in Deep-sleep mode, the clock source should be switched to IRC before entering Deep-sleep mode, because the IRC can be switched on and off glitch-free.

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There are three levels of Code Read Protection:

1. CRP1 disables access to chip via the SWD and allows partial flash update (excluding flash sector 0) using a limited set of the ISP commands. This mode is useful when CRP is required and flash field updates are needed but all sectors can not be erased.
2. CRP2 disables access to chip via the SWD and only allows full flash erase and update using a reduced set of the ISP commands.
3. Running an application with level CRP3 selected fully disables any access to chip via the SWD pins and the ISP. This mode effectively disables ISP override using PIO0_1 pin, too. It is up to the user's application to provide (if needed) flash update mechanism using IAP calls or call reinvoke ISP command to enable flash update via UART.

CAUTION

If level three Code Read Protection (CRP3) is selected, no future factory testing can be performed on the device.

7.19.5 Boot loader

The boot loader controls initial operation after reset and also provides the means to program the flash memory. This could be initial programming of a blank device, erasure and re-programming of a previously programmed device, or programming of the flash memory by the application program in a running system.

The boot loader code is executed every time the part is reset or powered up. The loader can either execute the ISP command handler or the user application code, or, on the LPC1342/43, it can program the flash image via an attached MSC device through USB (Windows operating system only). A LOW level during reset applied to the PIO0_1 pin is considered as an external hardware request to start the ISP command handler or the USB device enumeration. The state of PIO0_3 determines whether the UART or USB interface will be used (LPC1342/43 only).

7.19.6 APB interface

The APB peripherals are located on one APB bus.

7.19.7 AHB-Lite

The AHB-Lite connects the instruction (I-code) and data (D-code) CPU buses of the ARM Cortex-M3 to the flash memory, the main static RAM, and the boot ROM.

7.19.8 External interrupt inputs

All GPIO pins can be level or edge sensitive interrupt inputs. In addition, start logic inputs serve as external interrupts (see Section 7.19.1).

7.19.9 Memory mapping control

The Cortex-M3 incorporates a mechanism that allows remapping the interrupt vector table to alternate locations in the memory map. This is controlled via the Vector Table Offset Register contained in the NVIC.

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Table 7. Static characteristics *…continued*
T_{amb} = −40 °C to +85 °C, unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ[1]	Max	Unit
I_{OH}	HIGH-level output current	2.5 V ≤ V_{DD} ≤ 3.6 V; V_{OH} = V_{DD} − 0.4 V		20	-	-	mA
		2.0 V ≤ V_{DD} < 2.5 V; V_{OH} = V_{DD} − 0.4 V;		12	-	-	mA
I_{OL}	LOW-level output current	2.5 V ≤ V_{DD} ≤ 3.6 V; V_{OL} = 0.4 V		4	-	-	mA
		2.0 V ≤ V_{DD} < 2.5 V; V_{OL} = 0.4 V		3	-	-	mA
I_{pd}	pull-down current	V_I = 5 V		10	50	150	µA
I_{pu}	pull-up current	V_I = 0 V		−15	−50	−85	µA
		V_{DD} < V_I < 5 V		0	0	0	µA
I^2C-bus pins (PIO0_4 and PIO0_5); see Figure 20							
V_{IH}	HIGH-level input voltage			0.7V_{DD}	-	-	V
V_{IL}	LOW-level input voltage			-	-	0.3V_{DD}	V
V_{hys}	hysteresis voltage			-	0.05V_{DD}	-	V
I_{OL}	LOW-level output current	V_{OL} = 0.4 V; I^2C-bus pins configured as standard mode pins					
		2.5 V ≤ V_{DD} ≤ 3.6 V		3.5	-	-	mA
		2.0 V ≤ V_{DD} < 2.5 V		3.0	-	-	mA
I_{OL}	LOW-level output current	V_{OL} = 0.4 V; I^2C-bus pins configured as Fast-mode Plus pins					
		2.5 V ≤ V_{DD} ≤ 3.6 V		20	-	-	mA
		2.0 V ≤ V_{DD} < 2.5 V		16	-	-	
I_{LI}	input leakage current	V_I = V_{DD}	[16]	-	2	4	µA
		V_I = 5 V		-	10	22	µA
Oscillator pins							
$V_{i(xtal)}$	crystal input voltage			−0.5	+1.8	+1.95	V
$V_{o(xtal)}$	crystal output voltage			−0.5	+1.8	+1.95	V
USB pins (LPC1342/43 only)							
I_{OZ}	OFF-state output current	0 V < V_I < 3.3 V	[17]	-	-	±10	µA
V_{BUS}	bus supply voltage		[17]	-	-	5.25	V
V_{DI}	differential input sensitivity voltage	|(D+) − (D−)|	[17]	0.2	-	-	V
V_{CM}	differential common mode voltage range	includes V_{DI} range	[17]	0.8	-	2.5	V
$V_{th(rs)se}$	single-ended receiver switching threshold voltage		[17]	0.8	-	2.0	V
V_{OL}	LOW-level output voltage	for low-/full-speed; R_L of 1.5 kΩ to 3.6 V	[17]	-	-	0.18	V

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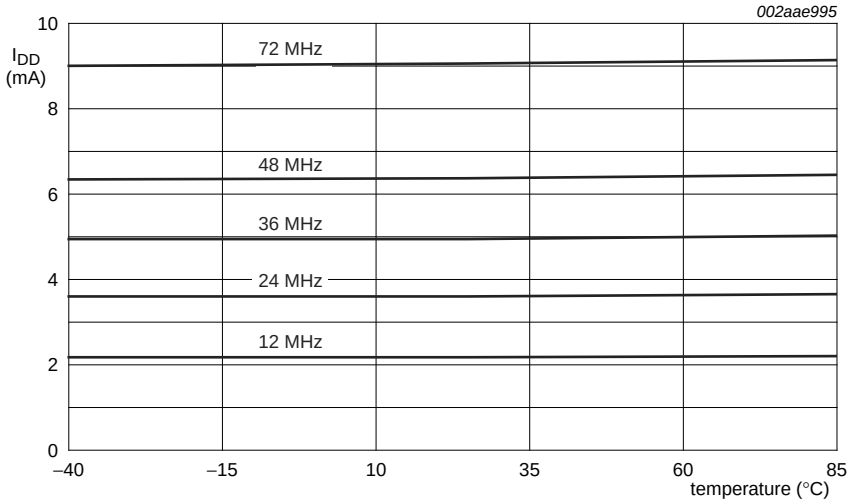
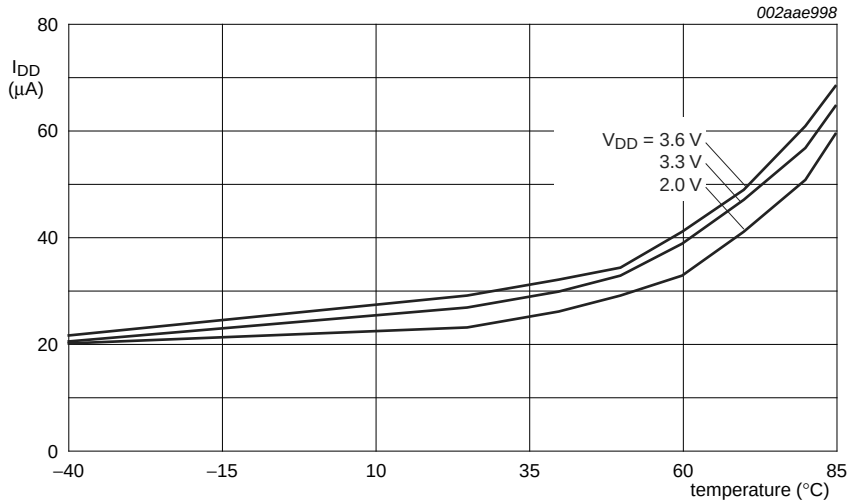


Conditions: V_{DD} = 3.3 V; Sleep mode entered from flash; internal pull-up resistors disabled; system oscillator and system PLL enabled; IRC, BOD disabled; all peripherals disabled in the SYSAHBCLKCTRL register (SYSAHBCLKCTRL = 0x1F); all peripheral clocks disabled; USB_DP and USB_DM pulled LOW externally (LPC1342/43).

Fig 11. Typical supply current versus temperature in Sleep mode (LPC1311/13/42/43)



Conditions: BOD disabled; all oscillators and analog blocks turned off in the PDSLEEPCFG register; PDSLEEPCFG = 0x0000 0FFF; USB_DP and USB_DM pulled LOW externally (LPC1342/43).

Fig 12. Typical supply current versus temperature in Deep-sleep mode (analog blocks disabled; LPC1311/13/42/43)

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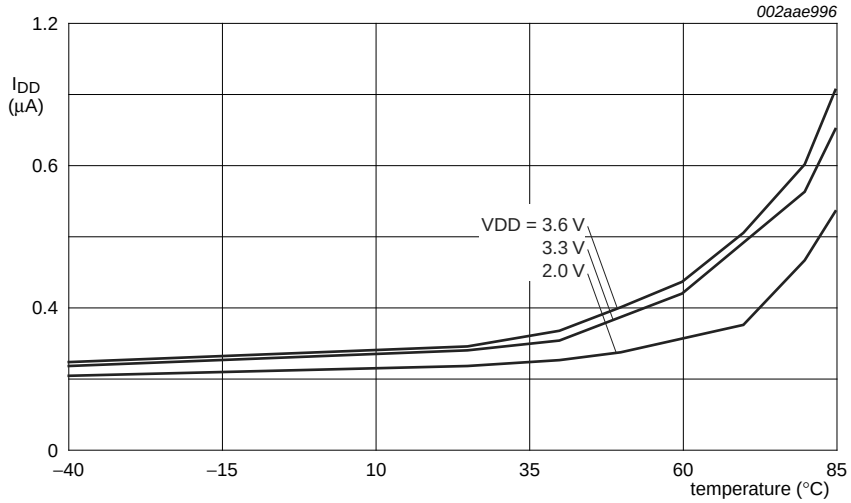

Fig 13. Typical supply current versus temperature in Deep power-down mode (LPC1311/13/42/43)

9.4 Power consumption for LPC1300L series (LPC1311/01 and LPC1313/01)

Remark: Applies to parts LPC1311/01 and LPC1313/01 and all their packages.

Power measurements in Active, Sleep, and Deep-sleep modes were performed under the following conditions (see *LPC13xx user manual*):

- Configure all pins as GPIO with pull-up resistor disabled in the IOCONFIG block.
- Configure GPIO pins as outputs using the GPIOnDIR registers.
- Write 0 to all GPIOnDATA registers to drive the outputs LOW.

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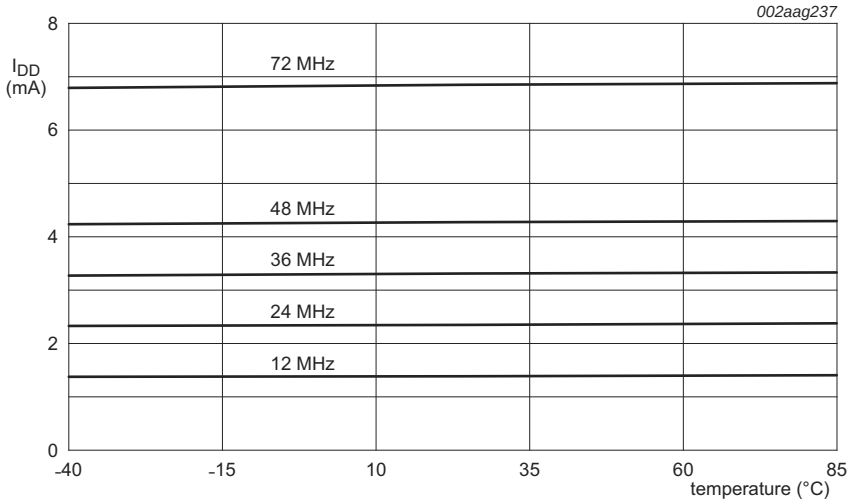
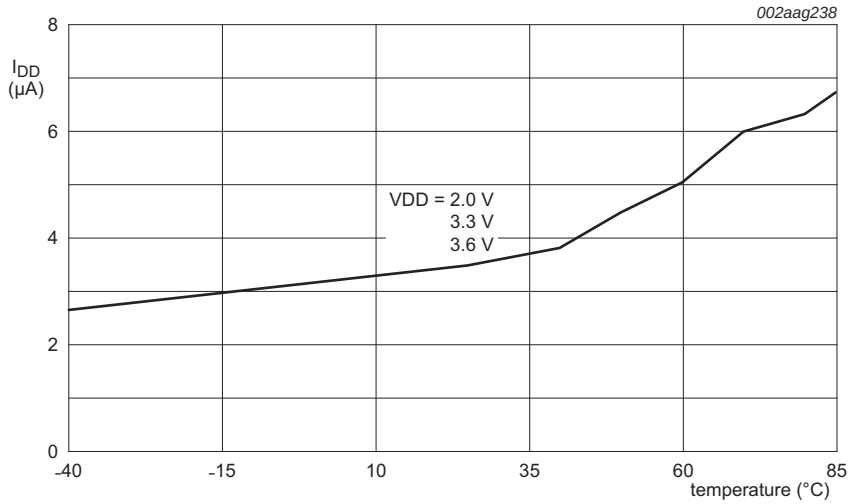


Conditions: V_{DD} = 3.3 V; Sleep mode entered from flash; internal pull-up resistors disabled; system oscillator and system PLL enabled; IRC, BOD disabled; all peripherals disabled in the SYSAHBCLKCTRL register (SYSAHBCLKCTRL = 0x1F); all peripheral clocks disabled; low-current mode.

Fig 16. Typical supply current versus temperature in Sleep mode (LPC1311/01 and LPC1313/01)



Conditions: BOD disabled; all oscillators and analog blocks turned off in the PDSLEEPCFG register; PDSLEEPCFG = 0x0000 0FFF.

Fig 17. Typical supply current versus temperature in Deep-sleep mode (analog blocks disabled, LPC1311/01 and LPC1313/01)

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10.3 External clock

Table 14. Dynamic characteristic: external clock
T_{amb} = –40 °C to +85 °C; V_{DD} over specified ranges.[1]

Symbol	Parameter	Conditions	Min	Typ[2]	Max	Unit
f_{osc}	oscillator frequency		1	-	25	MHz
$T_{cy(clk)}$	clock cycle time		40	-	1000	ns
t_{CHCX}	clock HIGH time		$T_{cy(clk)} \times 0.4$	-	-	ns
t_{CLCX}	clock LOW time		$T_{cy(clk)} \times 0.4$	-	-	ns
t_{CLCH}	clock rise time		-	-	5	ns
t_{CHCL}	clock fall time		-	-	5	ns

[1] Parameters are valid over operating temperature range unless otherwise specified.

[2] Typical ratings are not guaranteed. The values listed are at room temperature (25 °C), nominal supply voltages.

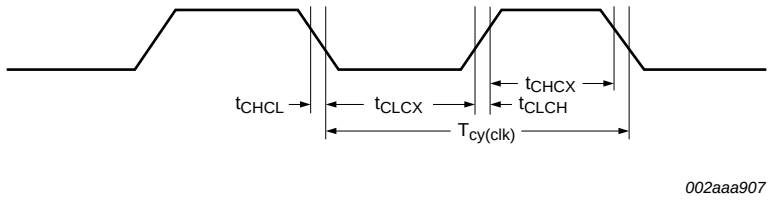

Fig 26. External clock timing (with an amplitude of at least $V_{i(RMS)}$ = 200 mV)

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10.7 SSP0/1 interface

Remark: The SSP1 interface is available on the LPC1313FBD48/01 only.

Table 19. Dynamic characteristics: SSP pins in SPI mode

Symbol	Parameter	Conditions		Min	Max	Unit
SSP master						
$T_{cy(clk)}$	clock cycle time	full-duplex mode	[1]	40	-	ns
		when only transmitting	[1]	27.8	-	ns
t_{DS}	data set-up time	in SPI mode; $2.4\ V \le V_{DD} \le 3.6\ V$	[2]	15	-	ns
		$2.0\ V \le V_{DD} < 2.4\ V$	[2]	20	-	ns
t_{DH}	data hold time	in SPI mode	[2]	0	-	ns
$t_{v(Q)}$	data output valid time	in SPI mode	[2]	-	10	ns
$t_{h(Q)}$	data output hold time	in SPI mode	[2]	0	-	ns
SSP slave						
$T_{cy(PCLK)}$	PCLK cycle time			13.9	-	ns
t_{DS}	data set-up time	in SPI mode	[3][4]	0	-	ns
t_{DH}	data hold time	in SPI mode	[3][4]	$3 \times T_{cy(PCLK)} + 4$	-	ns
$t_{v(Q)}$	data output valid time	in SPI mode	[3][4]	-	$3 \times T_{cy(PCLK)} + 11$	ns
$t_{h(Q)}$	data output hold time	in SPI mode	[3][4]	-	$2 \times T_{cy(PCLK)} + 5$	ns

[1] $T_{cy(clk)} = (SSPCLKDIV \times (1 + SCR) \times CPSDVSR) / f_{main}$. The clock cycle time derived from the SPI bit rate $T_{cy(clk)}$ is a function of the main clock frequency f_{main}, the SSP peripheral clock divider (SSPCLKDIV), the SSP SCR parameter (specified in the SSP0CR0 register), and the SSP CPSDVSR parameter (specified in the SSP clock prescale register).

[2] $T_{amb} = -40\ °C$ to $+85\ °C$.

[3] $T_{cy(clk)} = 12 \times T_{cy(PCLK)}$.

[4] $T_{amb} = 25\ °C$; $V_{DD} = 3.3\ V$.

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11. Application information

11.1 Suggested USB interface solutions (LPC1342/43 only)

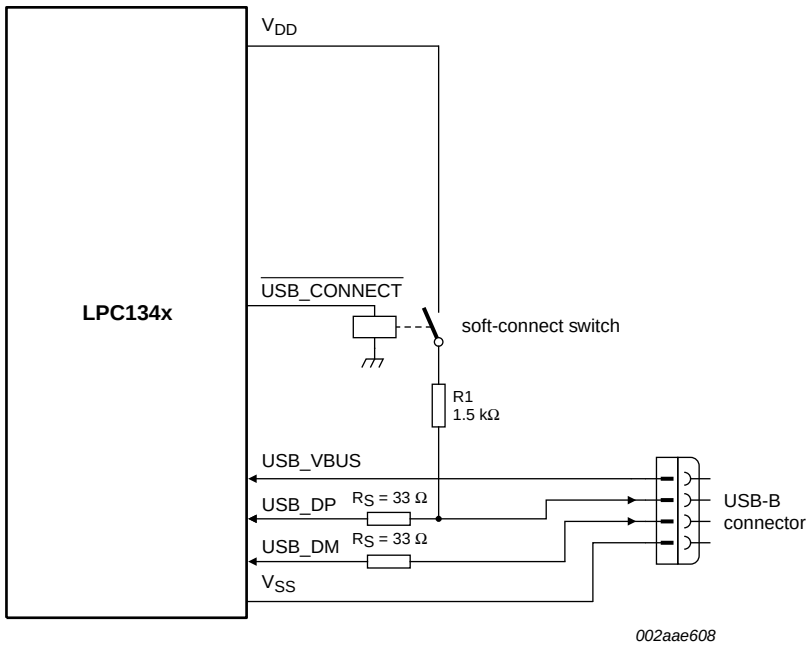

Fig 32. LPC1342/43 USB interface on a self-powered device

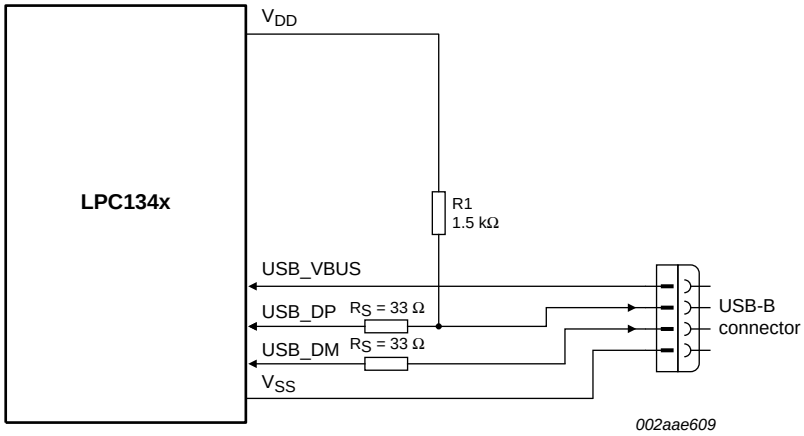

Fig 33. LPC1342/43 USB interface on a bus-powered device

11.2 XTAL input

The input voltage to the on-chip oscillators is limited to 1.8 V. If the oscillator is driven by a clock in slave mode, it is recommended that the input be coupled through a capacitor with C_i = 100 pF. To limit the input voltage to the specified range, choose an additional capacitor to ground C_g which attenuates the input voltage by a factor $C_i/(C_i + C_g)$. In slave mode, a minimum of 200 mV(RMS) is needed.

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Table 21. Recommended values for C_{X1}/C_{X2} in oscillation mode (crystal and external components parameters) low frequency mode

Fundamental oscillation frequency F_{OSC}	Crystal load capacitance C_L	Maximum crystal series resistance R_S	External load capacitors C_{X1}, C_{X2}
1 MHz - 5 MHz	10 pF	< 300 Ω	18 pF, 18 pF
	20 pF	< 300 Ω	39 pF, 39 pF
	30 pF	< 300 Ω	57 pF, 57 pF
5 MHz - 10 MHz	10 pF	< 300 Ω	18 pF, 18 pF
	20 pF	< 200 Ω	39 pF, 39 pF
	30 pF	< 100 Ω	57 pF, 57 pF
10 MHz - 15 MHz	10 pF	< 160 Ω	18 pF, 18 pF
	20 pF	< 60 Ω	39 pF, 39 pF
15 MHz - 20 MHz	10 pF	< 80 Ω	18 pF, 18 pF

Table 22. Recommended values for C_{X1}/C_{X2} in oscillation mode (crystal and external components parameters) high frequency mode

Fundamental oscillation frequency F_{OSC}	Crystal load capacitance C_L	Maximum crystal series resistance R_S	External load capacitors C_{X1}, C_{X2}
15 MHz - 20 MHz	10 pF	< 180 Ω	18 pF, 18 pF
	20 pF	< 100 Ω	39 pF, 39 pF
20 MHz - 25 MHz	10 pF	< 160 Ω	18 pF, 18 pF
	20 pF	< 80 Ω	39 pF, 39 pF

11.3 XTAL Printed-Circuit Board (PCB) layout guidelines

The crystal should be connected on the PCB as close as possible to the oscillator input and output pins of the chip. Take care that the load capacitors C_{x1}, C_{x2}, and C_{x3} in case of third overtone crystal usage have a common ground plane. The external components must also be connected to the ground plain. Loops must be made as small as possible in order to keep the noise coupled in via the PCB as small as possible. Also parasitics should stay as small as possible. Values of C_{x1} and C_{x2} should be chosen smaller accordingly to the increase in parasitics of the PCB layout.

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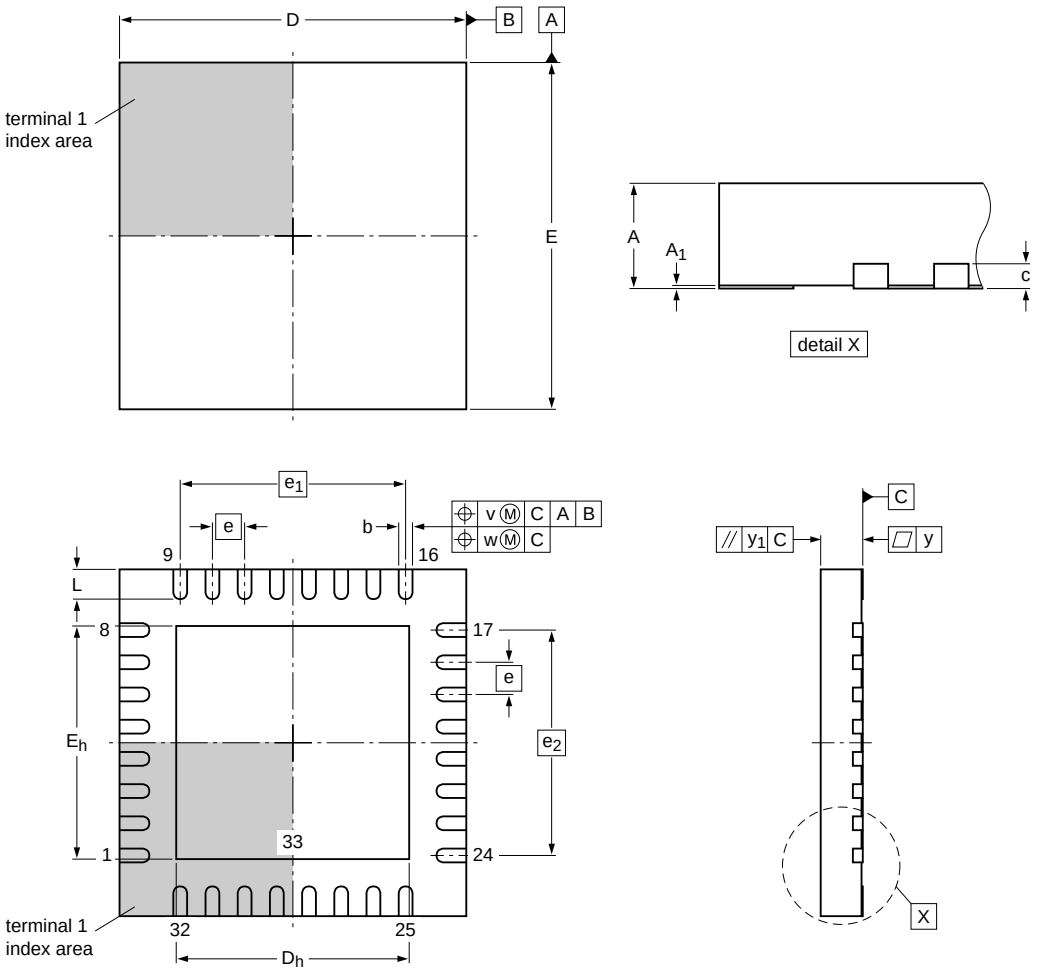
HVQFN33: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 x 7 x 0.85 mm



Dimensions

Unit		$A^{(1)}$	A_1	b	c	$D^{(1)}$	D_h	$E^{(1)}$	E_h	e	e_1	e_2	L	v	w	y	y_1
	max	1.00	0.05	0.35		7.1	4.85	7.1	4.85				0.75				
mm	nom	0.85	0.02	0.28	0.2	7.0	4.70	7.0	4.70	0.65	4.55	4.55	0.60	0.1	0.05	0.08	0.1
	min	0.80	0.00	0.23		6.9	4.55	6.9	4.55				0.45				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

hvqfn33_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
		- - -				~~09-03-17~~ 09-03-23

Fig 39. Package outline (HVQFN33)

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Footprint information for reflow soldering of HVQFN33 package

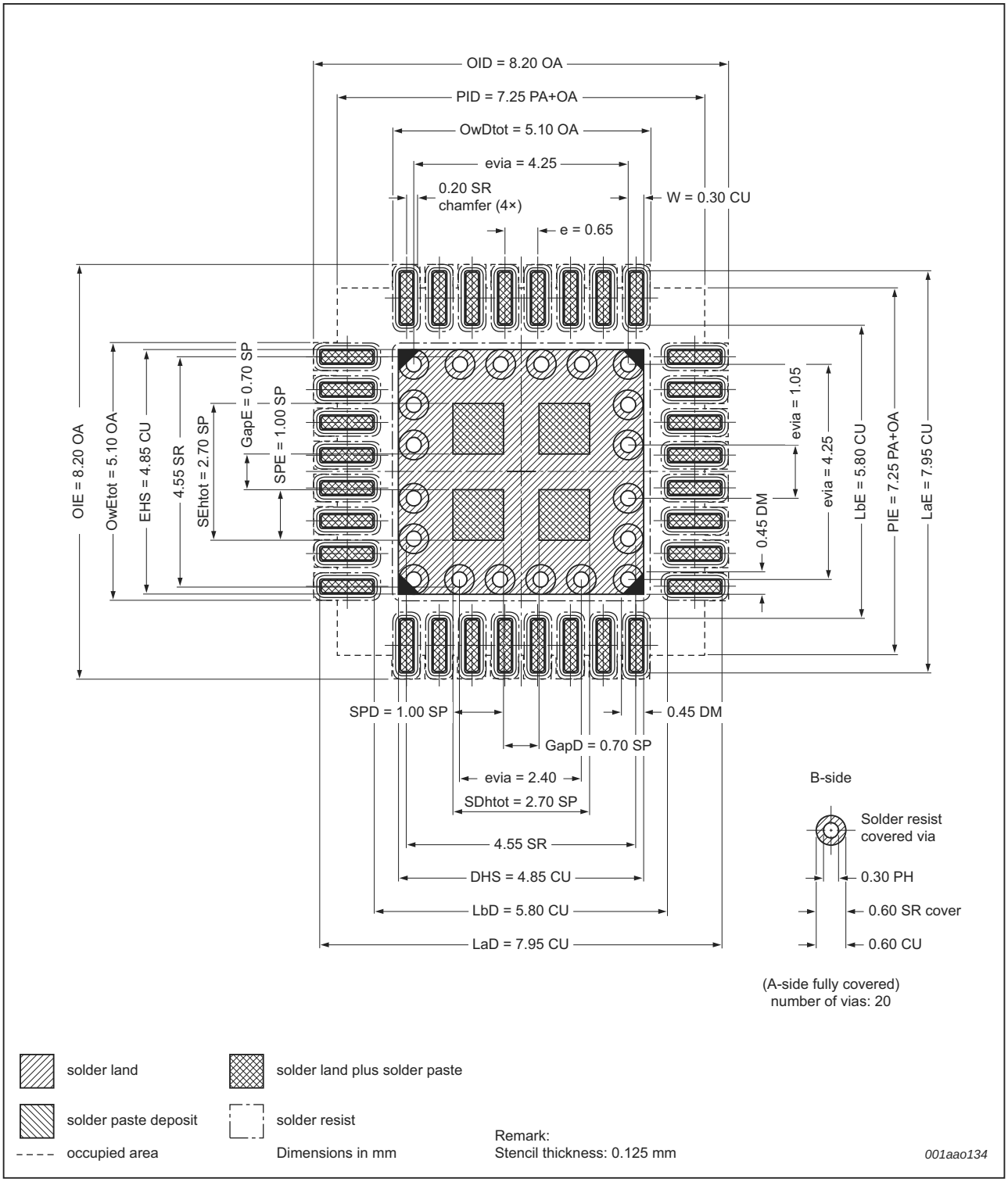

Fig 41. Reflow soldering of the HVQFN33 package

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14. Abbreviations

Table 24. Abbreviations

Acronym	Description
A/D	Analog-to-Digital
ADC	Analog-to-Digital Converter
AHB	Advanced High-performance Bus
AMBA	Advanced Microcontroller Bus Architecture
APB	Advanced Peripheral Bus
BOD	BrownOut Detection
EOP	End Of Packet
ETM	Embedded Trace Macrocell
FIFO	First-In, First-Out
GPIO	General Purpose Input/Output
HID	Human Interface Device
I/O	Input/Output
LSB	Least Significant Bit
MSC	Mass Storage Class
PHY	Physical Layer
PLL	Phase-Locked Loop
SE0	Single Ended Zero
SPI	Serial Peripheral Interface
SSI	Serial Synchronous Interface
SSP	Synchronous Serial Port
SoF	Start-of-Frame
TCM	Tightly-Coupled Memory
TTL	Transistor-Transistor Logic
UART	Universal Asynchronous Receiver/Transmitter
USB	Universal Serial Bus

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